



REACH ROHS Lead Free



The Power of LED Light

Typical Electrical & Optical Characteristics (IF=350mA and Ta=25°C)

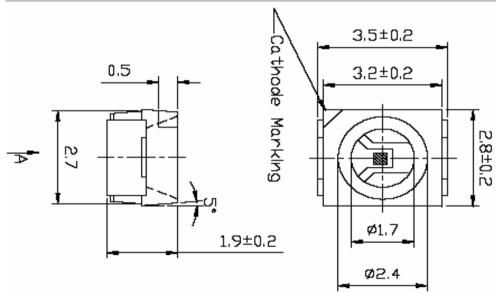
Part-No.	Dominant Wavelength (nm) or CCT(K)		Forward (l Voltage √)		ous Flux cd)	Cur- rent (mA)	50% Power Angle
	Min	Тур	Min	Max	Min	Тур	max	Тур
M11A1313	470	475	3,3	3,6	360	500,0	30	120

1. Tolerance of measurement of luminous flux : +/-15% 2. Tolerance of measurement of dominant Wavelength : +/-1nm

3. Tolerance of measurement of CCT (Correlated color temperature +/- 200K

4. Tolerance of measurement of forward voltage +/-0,1V

Technical Dimensions



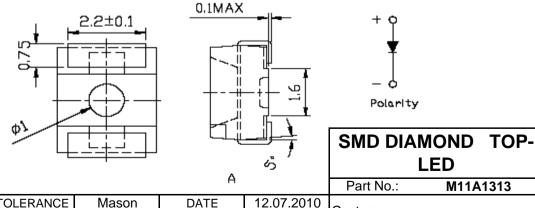
Contour Lights Garden Lighting Genral Lighting **Reading Lights**

Absulut Maximum Ratings (Ta=25°C)

Features

Items	Symb ols	Absulut maximum Rating	Unit
	OIS	Red	
Power Dissipation	Pd	850	mW
Forward Current	lf	350	mA
Peak Forward Current	lfp	500	Ma
LED Junction Temperature	Tj	125	°C
Operating Temperature	Topr	30°C ~ +110°C	°C
Storage Temperature	Tstg	40°C ~ +120°C	°C

* Pulse width $\leq 0,1$ msec duty $\leq 1/10$

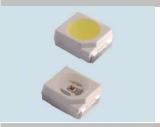


										Part No.:	M11A1313
DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010	Customer:	
APPD:	Schumi			FINISH	Jamy		Shee	t No.	1 from 10	Customer.	
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LED









										DII	GOID									
Code	Lu	uminous	Flux Ran	ge	Code	Lu	uminous	Flux Ran	ge				C.	ode		CCT F	≀ange		Co	
Code	m	nin	m	ax.	Code	m	nin	m	ax.	%!				Jue	Μ	lin	Ma	ax	0	u
А		1		2	P2	7	0	8	30	- 15			1	Ą	27	'00	29	000	Ν	Λ
В	:	2	2	.,5	M1	8	80	9	90	/+ s			E	В	29	000	31	00	Ν	1
С	2	,5	3	,2	M2	9	90	1	00	i xn			(C	31	00	33	00	F	5
D	3	,2		4	N1	10	00	1	10	с Б С			[D	33	800	35	00	C	ג
Е		4		5	N2	1	10	1	20	inor			I	E	35	500	37	00	R	2
F		5	6	,2	P1	1:	20	1	30	Tolerance of measurement of luminous Flux is +/- 15%			I	F	37	'00	39	00	S	5
G	6	,2	7	,7	P2	1:	30	1	40	of Ir			(G	39	000	41	00	Т	Ē
Н	7	,7	9	,6	Q1	14	40	1	50	ent			ŀ	ł	41	00	43	800	ι	J
J	9	,6	1	2	Q2	1:	50	1	60	ē				J	43	800	45	500	٧	1
К	1	2	1	5	R1	10	60	1	70	asur			ł	K	45	500	47	'00	V	V
L1	1	5	1	9	R2	1	70	1	80	mea			l	L	47	'00	49	000		
L2	1	9	2	24	S1	18	80	2	00	of			Tolerand	ce of mea	suremen	t of CCT i	s +/-100ł	К.		
M1	2	24	3	30	S2	20	00	2	20	nce										
M2	3	80	4	10	T1	2	20	2	40	lera										
N1	4	10	5	50	T2	24	40	2	60	To										
N2	5	50	6	60	U1	2	50	2	80											
P1	6	60	7	' 0																
		l	В	I	Н	G	/E		F	,	Y	G	/P	R	/U					
Color	[.] Code	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	of nm				
D	00	450	455	490	495	515	520	560	565	580	583	600	605	620	625	ent +/-1				
D	D1	455	460	495	500	520	525	565	570	583	586	605	610	625	630	is is				
D	02	460	465	500	505	525	530	570	575	586	589	610	615	630	635	gth				
D	03	465	470	505	510	530	535	575	580	589	592	615	620	635	640	mea				
D	04	470	475	510	515	535	540			592	595			640	645	e of				
D	05	475	480			540	545			595	598			645	650	nce nt v			Г	
D	06	480	485			545	550							650	655	lera iina				
D	07	485	490			550	555		1	1		1		655	660	Tolerance of measurement of dominant wavelength is +/-1nm				1
D	08					555	560							660	665	Ĩ			ľ	_
DR	RW:	Ja	son	C⊢	IKD	Wil	son	MA	TL:	Wi	son	TOLE	RANCE	Ma	son	DA	TE	12.07.2	010	<i>c</i>
AP	PD:	Sch	numi					FIN	IISH	Ja	my				Shee	t No.		2 from	10	
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BIN GUIDE / HIGH POWER

Code	CCTI	Range	Code	CCT Range			
Code	Min	Max	Code	Min	Max		
А	2700	2900	М	4900	5100		
В	2900	3100	Ν	5100	5500		
С	3100	3300	Р	5500	6000		
D	3300	3500	Q	6000	6500		
E	3500	3700	R	6500	7000		
F	3700	3900	S	7000	7500		
G	3900	4100	Т	7500	8000		
Н	4100	4300	U	8000	9000		
J	4300	4500	V	9000	10000		
К	4500	4700	W	10000	12000		
L	4700	4900					

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Part No.:

Customer:

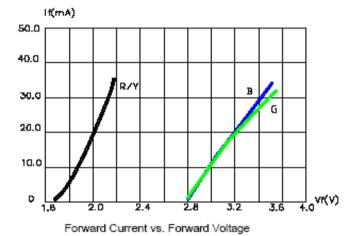
SMD DIAMOND TOP-LED

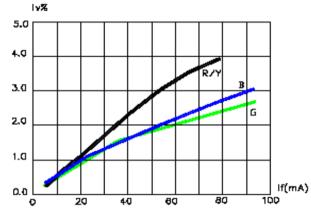
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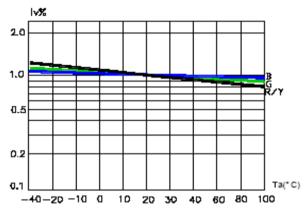


Typical Electrical / Optical Characteristics Curves (Ta=25°C Unless otherwise noted)

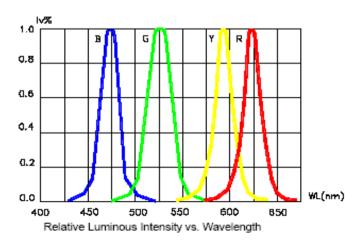








Relative Luminous Intensity vs. Ambient Temperature



Code	Forward Voltage Rank						
Code	Min.	Max.					
А	1,6	1,8					
В	1,8	2,0					
С	2,0	2,2					
D	2,2	2,4					
E	2,4	2,6					
F	2,6	2,8					
G	2,8	3,0					
Н	3,0	3,2					

Code	Forward Voltage Rank						
Code	Min.	Max.					
J	3,20	3,40					
K	3,40	3,60					
L	3,60	3,80					
М	3,80	4,00					
N	4,00	4,20					
Р	4,20	4,40					
Q	4,40	4,60					
R	4,60	4,80					

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Tolerance of measurement of forward voltage is +/-0,1V

	SMD DIAMOND TOP- LED										
	Part No.:	M11A1313									
0)	Customer:										

DRW: CHKD Wilson MATL: Wilson TOLERANCE 12.07.201 Mason DATE Jason APPD: FINISH Schumi Sheet No. 3 from 10 Jamy

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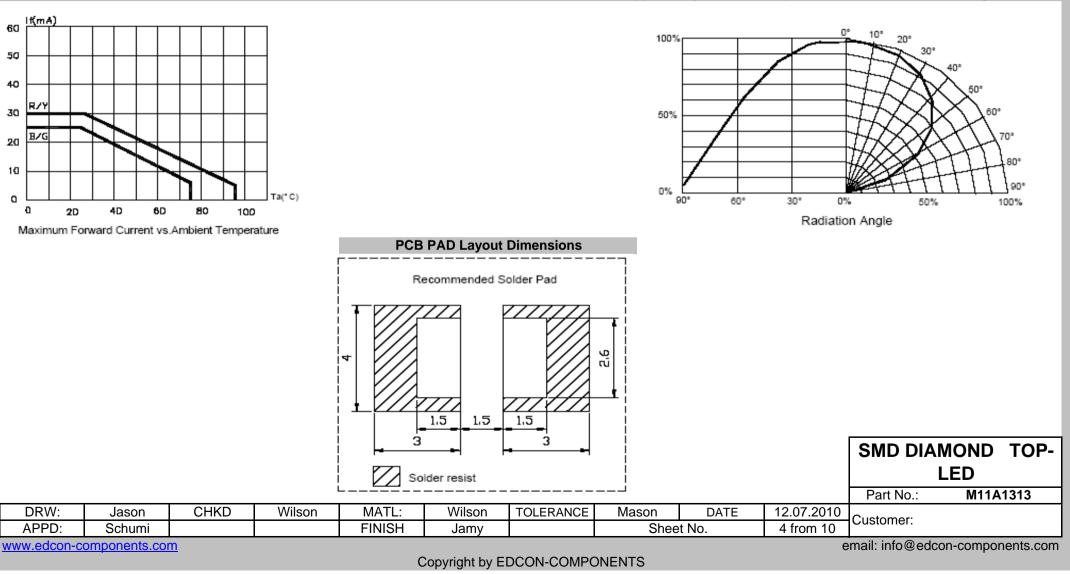
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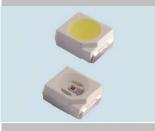
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Typical Representative Spatial Radiation Paddern of single LED









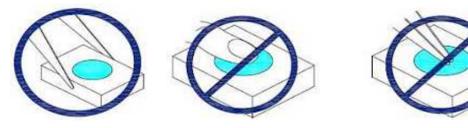


Handling Informations

- 4. The outer diameter of the TOP LED pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although ist characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of th LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools



2. Do not directly touch or handle the silicone lens surfance. It may damage the internal circuitry.

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	\geq

3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratsch the silicone lens or damage the internal circuitry.



SMD DIAN	MOND	TOP-
l	ED	
Part No.:	M11A	1313

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010	Customor	
APPD:	Schumi			FINISH	Jamy		Shee	et No.	5 from 10	Customer:	

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Moisture Proof Packing

In Order to prevent moisture absorption into DIAMOND = TOP LED / XEON POWER during the transportation and storage. DIAMOND TOP-LED / XEON-POWER LED is packed in a moisture barrier bag. Desiccants and humidity indicator are packed together with DIAMOND TOP-LED / XEON-POWER LED as the secondary protection. The indication of humidity card provides the information of humidity within TOP Packing.

Storage

Shelf life in original sealed bag in storage condition of <40°C and 90% RH is 12 mounths. Baking is required whenever shelf life is expired. Before opening the packaging please check wether bag leak air or not. After opening the DIAMOND TOP-LED / XEON POWER LED must be storad under the condition <30°C and 60% RH. Under this condition DIAMOND TOP-LED / XEON POWER LED must be used (subject to reflow) within 24-hours after bag opening, and re-baking is required when exceeding 24 hours. For baking, place DIAMOND TOP-LED / XEON POWER LED in oven at temperature 75°C +/-5°C and relative humidity <10%RH, for 24 hours. Take out the material from packaging bag for re-bake. Do not open the door of oven frequently during the baking process.

Manual soldering (We do not recommend this method strongly).

No mechanical stress should be exerted on the resin portion of DIAMOND TOP-LED / XEON POWER during soldering.

Handling of DIAMOND TOP-LED / XEON POWER LED should be done when the package has been cooled down to below 40°C or less. This is to prevent the DIAMOND

TOP-LED / XEON POWER failures due the thermal-mechanical strss during handling.

Reflow soldering should not be done more than one time.

No stress should be exerted on the package during soldering.

Electrostatic Discharge and Surge current.

Electrostatic discharge (ESD) or surge current (EOS) may damage LED.

Precautions such as ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling DIAMOND TOP-LED / XEON POWER LED.

All devices, equipment and machinery must be prpertly grounded.

It is recommended to perform electrical test to screen out ESD failures in final inspection.

It is importate to eliminate the possibility of surge current during circuity design.

Heat Management

Heat management of DIAMOND TOP-LED / XEON POWER must be taken into into consideration during the design stage of DIAMOND TOP-LED / XEON POWER LED application. The current should be de-rated appropriately by refering to the de-rating curve attached on each product specification.

										SMD DIA	LED	
										Part No.:	M11A1313	
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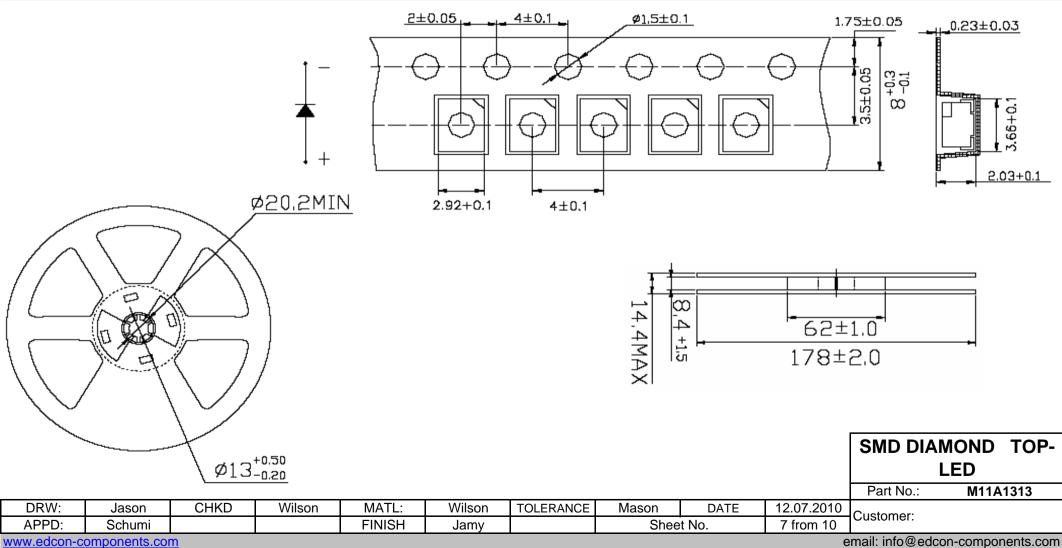
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Packing Specifications



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EDCON-COMPONENTS RoHS Lead Free REACH D COMPONENTS A MEMBER OF EDCON-GROUP The Power of LED Light **Ordering Informations**

	Serie	Color Code	ROHS	Packing				
_								
Γ	M11A1313	BL	R	TR				

BL = Blue	R= ROHS	TR= TAPE			
DL = Diue	Conform	REEL			
	N= NON	BU= Bulk-			
	ROHS	Ware			

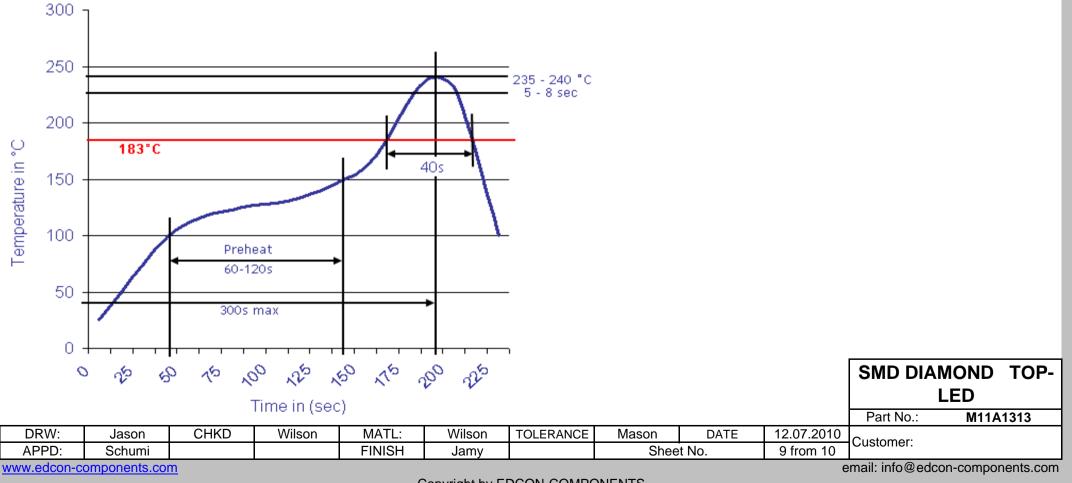
										SMD DIAMOND TOP- LED	
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Classification Reflow Profile (JEDEC J-STD-020C)



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DRW:

APPD:

Jason

Schumi

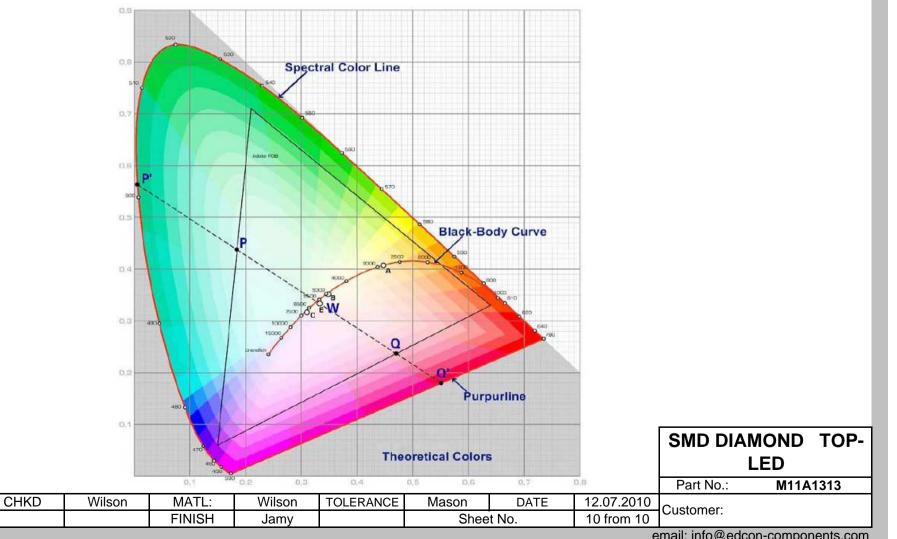
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Spectral Color Curve



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